TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS070B – Revised June 2003

CD4508B Types

CMOS Dual 4-Bit Latch

High-Voltage Types (20-Volt Rating)

■ CD4508B dual 4-bit latch contains two identical 4-bit latches with separate STROBE, RESET, and OUTPUT DISABLE controls. With the STROBE line in the high state, the data on the "D" inputs appear at the corresponding "Q" outputs provided the DISABLE line is in the low state. Changing the STROBE line to the low state locks the data into the latch. A high on the reset line forces the outputs to a low level regardless of the state of the STROBE input. The outputs are forced to the high-impedance state for bus line applications by a high level on the DISABLE input.

The CD4508B types are supplied in 24-lead hermetic dual-in-line ceramic packages (F3A suffix), 24-lead dual-in-line plastic packages (E suffix), 24-lead small-outline packages (M, M96, and NSR suffixes), and 24-lead thin shrink small-outline packages (PW and PWR suffixes).

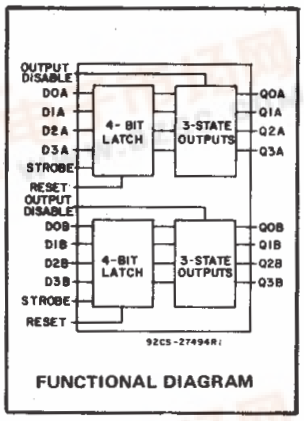
The CD4508B is similar to industry type MC14508.

Features:

- Two independent 4-bit latches
- Individual master reset for each 4-bit latch
- 3-state outputs with high-impedance state for bus line applications
- Medium-speed operation: $t_{PHL} = t_{PLH} = 70$ ns (typ.) at $V_{DD} = 10$ V and $C_L = 50$ pF
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Standardized, symmetrical output characteristics
- Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) =
  1 V at V_{DD} = 5 V
  2 V at V_{DD} = 10 V
  2.5 V at V_{DD} = 15 V
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

- Buffer storage
- Holding registers
- Data storage and multiplexing



FUNCTIONAL DIAGRAM

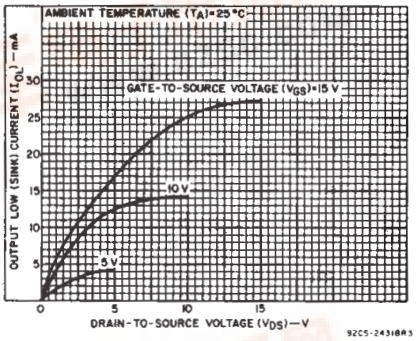


Fig.2 – Typical output low (sink) current characteristics.

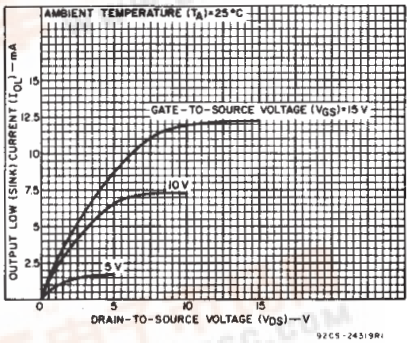


Fig.3 – Minimum output low (sink) current characteristics.

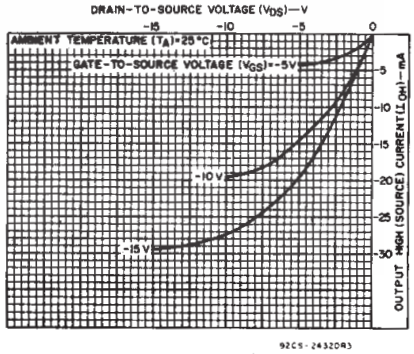


Fig.4 – Typical output high (source) current characteristics.

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

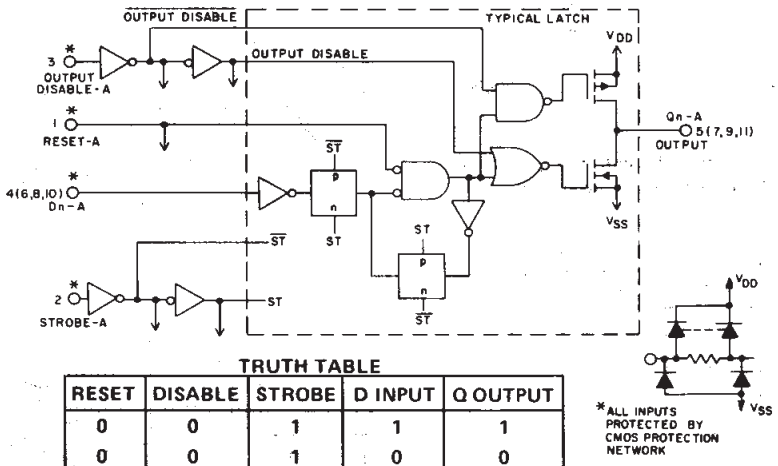
RECOMMENDED OPERATING CONDITIONS at T_A = 25°C, Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} (V)	LIMITS Min.	LIMITS Max.	UNITS
Supply-Voltage Range (For T_A = Full Package-Temperature Range)		3	18	V
Reset Pulse Width, $t_{W(R)}$	5	200	–	ns
	10	140	–	
	15	100	–	
Strobe Pulse Width, $t_{W(st)}$	5	140	–	
	10	80	–	
	15	70	–	
Setup Time, t_{SU}	5	50	–	
	10	30	–	
	15	20	–	
Hold Time, t_H	5	0	–	
	10	0	–	
	15	0	–	

3 COMMERCIAL CMOS HIGH VOLTAGE ICs

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								+25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	–	0,5	5	5	5	150	150	–	0.04	5	μA
	–	0,10	10	10	10	300	300	–	0.04	10	
	–	0,15	15	20	20	600	600	–	0.04	20	
	–	0,20	20	100	100	3000	3000	–	0.08	100	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	–	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	–	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	–	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	–	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	–	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	–	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	–	
Output Voltage: Low-Level, V_{OL} Max.	–	0,5	5	0.05				–	0	0.05	V
	–	0,10	10	0.05				–	0	0.05	
	–	0,15	15	0.05				–	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage, V_{IL} Max.	0.5, 4.5	–	5	1.5				—	—	1.5	V
	1, 9	–	10	3				—	—	3	
	1.5,13.5	–	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5, 4.5	–	5	3.5				3.5	—	—	
	1, 9	–	10	7				7	—	—	
	1.5,13.5	–	15	11				11	—	—	
Input Current I_{IN} Max.	–	0,18	18	±0.1	±0.1	±1	±1	–	$\pm 10^{-5}$	±0.1	μA
3-State Output Leakage Current I_{OUT} Max.	0,18	0,18	18	±0.4	±0.4	±12	±12	–	$\pm 10^{-4}$	±0.4	μA



TRUTH TABLE

RESET	DISABLE	STROBE	D INPUT	Q OUTPUT
0	0	1	1	1
0	0	1	0	0
0	0	0	X	LATCHED
1	0	X	X	0
X	1	X	X	Z

1 = HIGH LEVEL X = DON'T CARE
0 = LOW LEVEL Z = HIGH IMPEDANCE

Fig. 7 — Logic diagram (A-Section), 1 of 4 identical latches with common output disable, reset, and strobe.

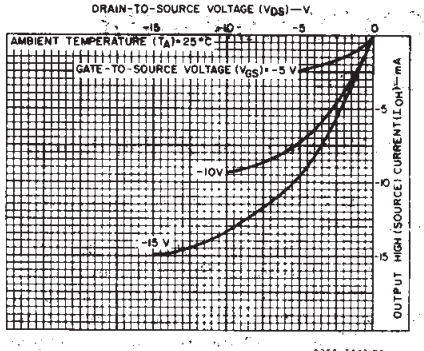


Fig. 4 — Minimum output high (source) current characteristics.

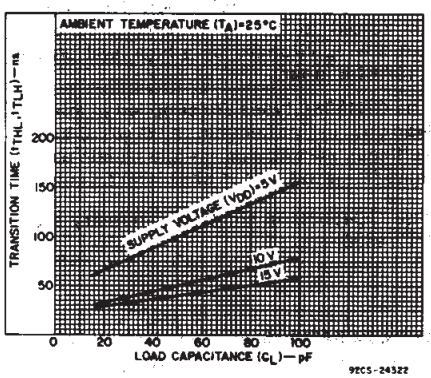


Fig. 5 — Typical transition time as a function of load capacitance.

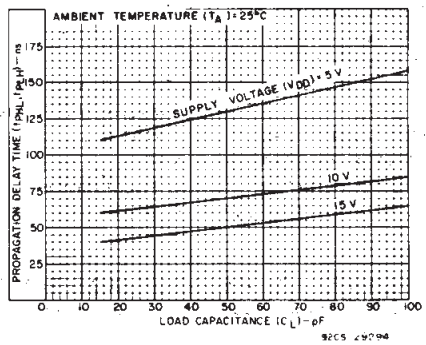


Fig. 6 — Typical propagation delay time as a function of load capacitance (strobe to data out).

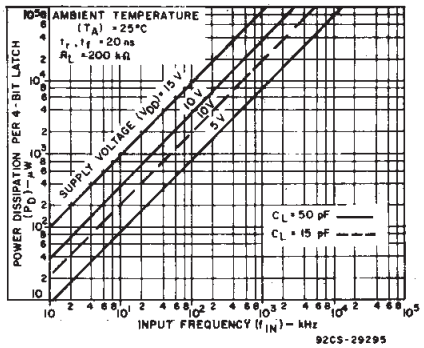


Fig. 8 — Typical power dissipation as a function of frequency.

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C; Input t_r, t_f = 20 ns, C_L = 50 pF, R_L = 200 kΩ, unless otherwise specified.

CHARACTERISTIC	TEST CONDITIONS	V_{DD}	LIMITS Typ.	LIMITS Max.	UNITS
Transition Time, t_{THL}, t_{TLH}		5	100	200	ns
		10	50	100	
		15	40	80	
Minimum Reset Pulse Width, $t_{W(R)}$		5	100	200	
		10	70	140	
		15	50	100	
Minimum Strobe Pulse Width, $t_{W(st)}$		5	70	140	
		10	40	80	
		15	35	70	
Minimum Setup Time, t_{SU}		5	25	50	
		10	15	30	
		15	10	20	
Minimum Hold Time, t_H		5	0	0	
		10	0	0	
		15	0	0	
Propagation Delay Times: t_{PHL}, t_{PLH} Strobe to Data Out		5	130	260	
		10	70	140	
		15	50	100	
Data In to Data Out		5	105	210	
		10	60	120	
		15	45	90	
Reset to Data Out		5	90	180	
		10	50	100	
		15	40	80	
3-State Propagation Delay Times: Output High to High Impedance, t_{PHZ}		5	90	180	
		10	50	100	
		15	35	70	
High Impedance to Output High, t_{PZH}		5	90	180	
		10	50	100	
		15	35	70	
Output Low to High Impedance, t_{PLZ}		5	90	180	
		10	50	100	
		15	35	70	
High Impedance to Output Low, t_{PZL}		5	90	180	
		10	50	100	
		15	35	70	
Input Capacitance, C_{IN}	Any Input	–	5	7.5	pF

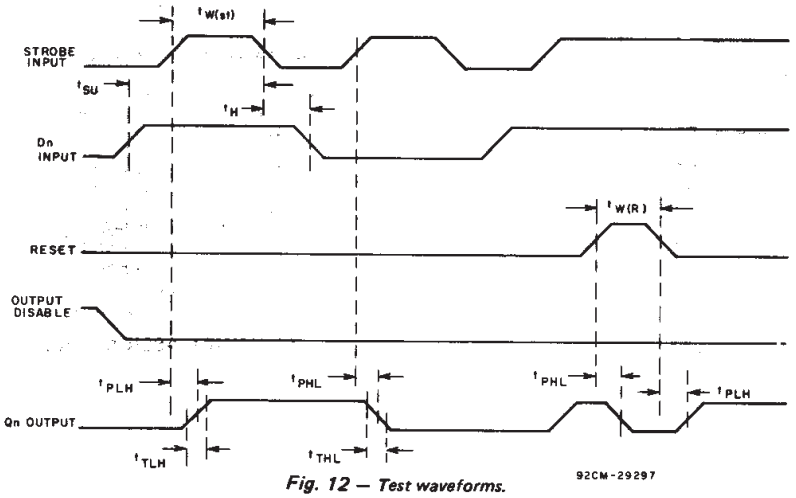


Fig. 12 — Test waveforms.

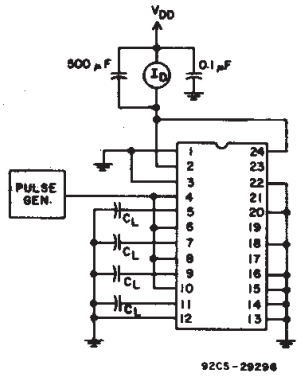


Fig.9 — Power dissipation test circuit.

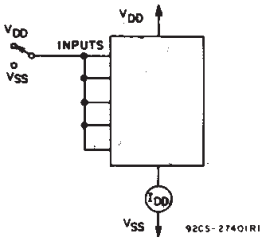


Fig.10 — Quiescent device current test circuit.

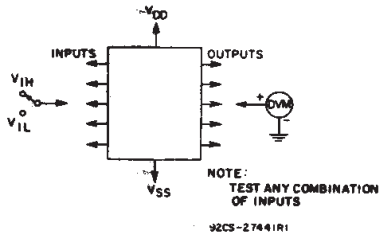


Fig.11 — Input voltage test circuit.

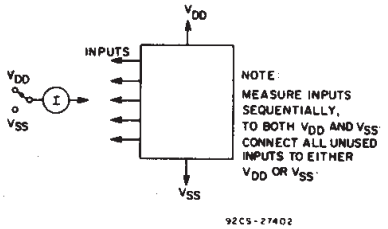
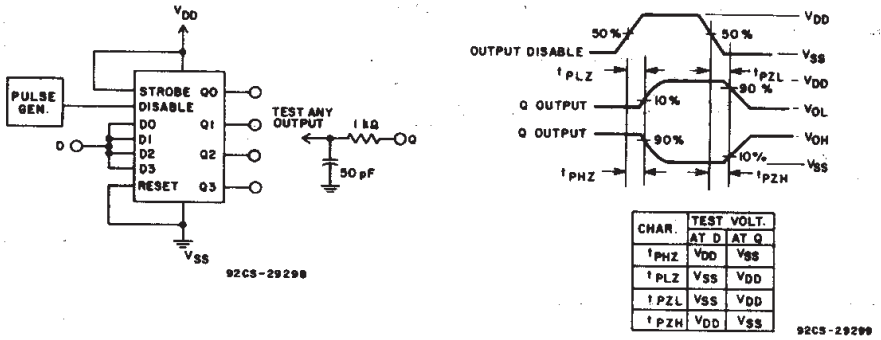


Fig. 13 — Input current test circuit.



CHAR.	TEST VOLT. AT D	AT Q
t_{PHZ}	V_{DD}	V_{SS}
t_{PLZ}	V_{SS}	V_{DD}
t_{PZL}	V_{SS}	V_{DD}
t_{PZH}	V_{DD}	V_{SS}

Fig. 14 – Output disable test circuit and waveforms.

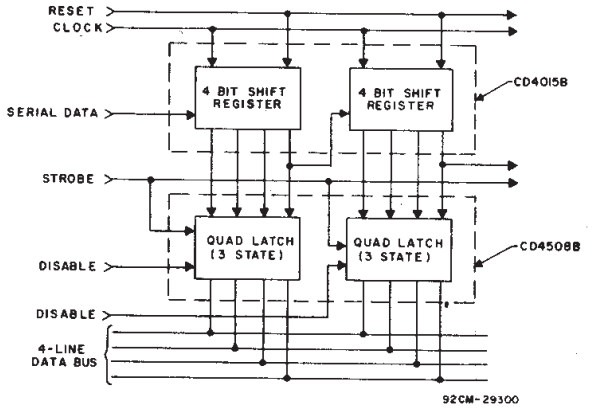
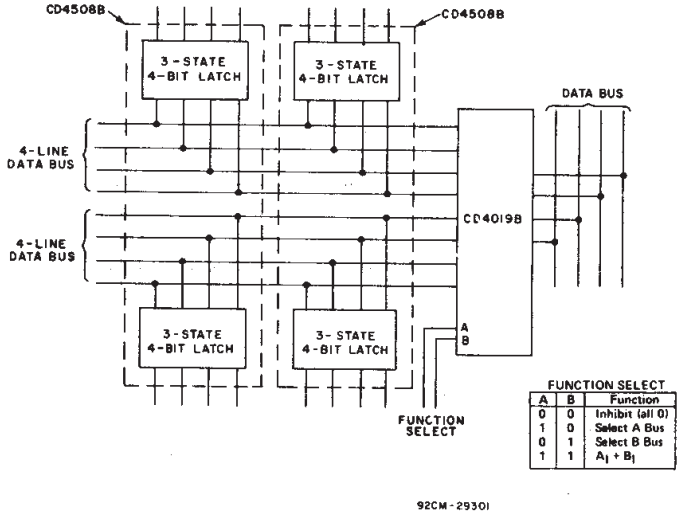
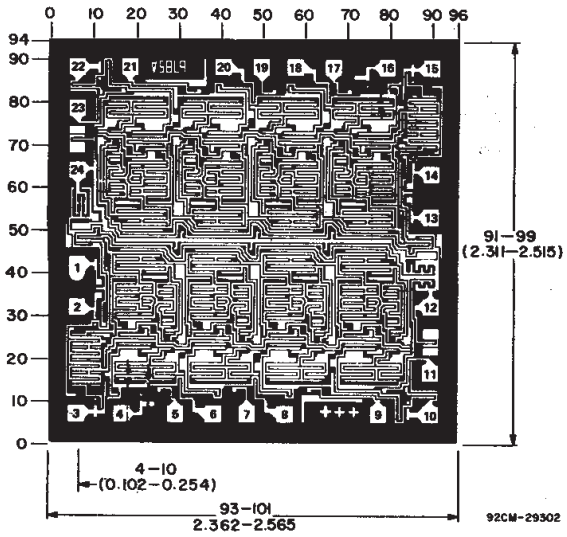


Fig. 15 – Bus register.



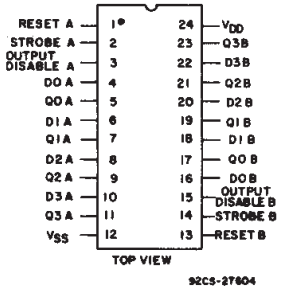
FUNCTION SELECT		
A	B	Function
0	0	Inhibit (all 0)
1	0	Select A Bus
0	1	Select B Bus
1	1	$A_I + B_I$

Fig. 16 – Dual multiplexed bus register with function select.



Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

Chip dimensions and pad layout for CD4508B.



TERMINAL ASSIGNMENT

PACKAGE OPTION ADDENDUM

28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CD4508BD3	ACTIVE	CDIP SB	JD	24	1	None	Call TI	Level-NC-NC-NC
CD4508BE	ACTIVE	PDIP	N	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4508BF3A	ACTIVE	CDIP	J	24	1	None	Call TI	Level-NC-NC-NC
CD4508BM	ACTIVE	SOIC	DW	24	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD4508BM96	ACTIVE	SOIC	DW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD4508BNSR	ACTIVE	SO	NS	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD4508BPW	ACTIVE	TSSOP	PW	24	60	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4508BPWR	ACTIVE	TSSOP	PW	24	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

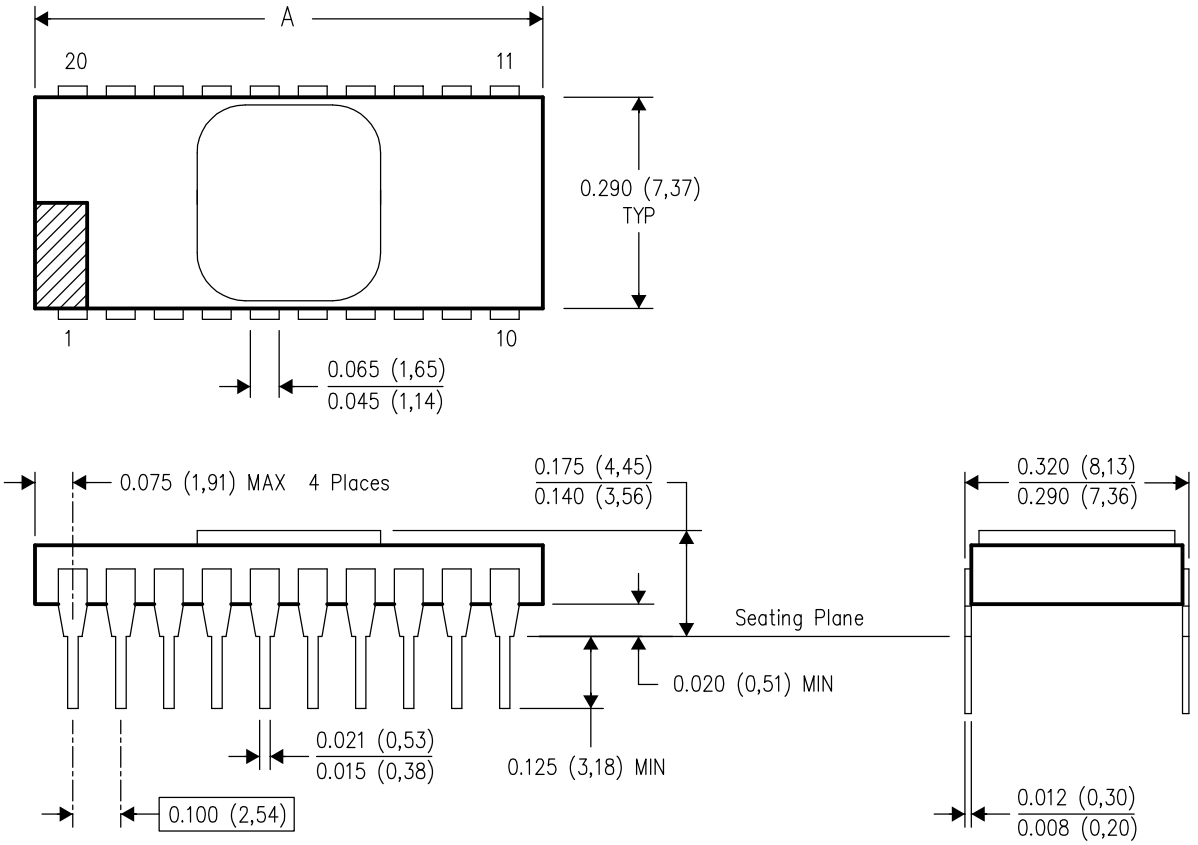
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
None: Not yet available Lead (Pb-Free).
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

JD (R–CDIP–T**) CERAMIC SIDE–BRAZE DUAL–IN–LINE PACKAGE

20 PINS SHOWN



DIM \ PINS **	8	14	16	18	20	24
A MAX	0.405 (10,29)	0.757 (19,23)	0.810 (20,57)	0.910 (23,11)	1.010 (25,65)	1.100 (27,94)

4040086–2/F 07/03

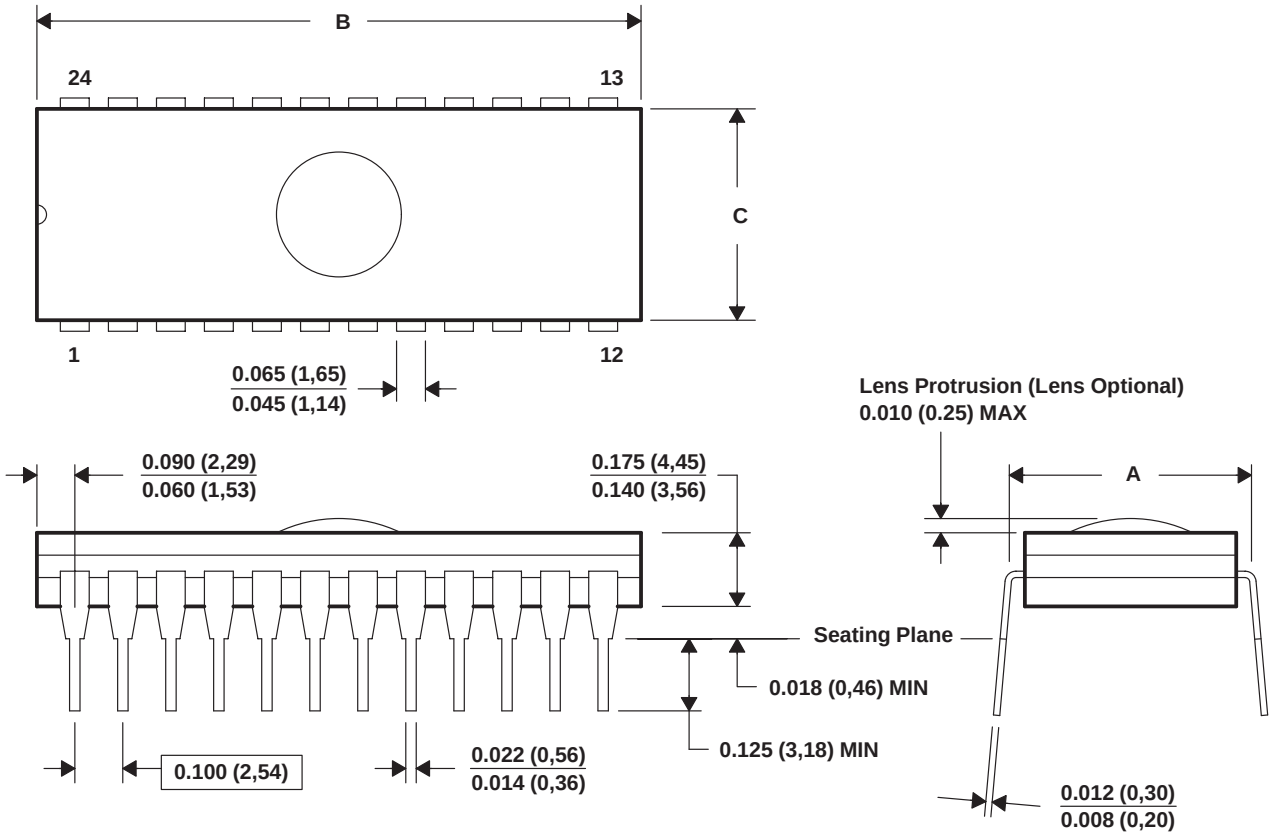
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within MIL STD 1835 CDIP2 – T8, T14, T16, T18, T20 and T24 respectively.

MCDI004A – JANUARY 1995 – REVISED NOVEMBER 1997

J (R-GDIP-T**)

CERAMIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



DIM	PINS **	24		28		32		40	
		NARR	WIDE	NARR	WIDE	NARR	WIDE	NARR	WIDE
"A"	MAX	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)	0.624(15,85)
	MIN	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)	0.590(14,99)
"B"	MAX	1.265(32,13)	1.265(32,13)	1.465(37,21)	1.465(37,21)	1.668(42,37)	1.668(42,37)	2.068(52,53)	2.068(52,53)
	MIN	1.235(31,37)	1.235(31,37)	1.435(36,45)	1.435(36,45)	1.632(41,45)	1.632(41,45)	2.032(51,61)	2.032(51,61)
"C"	MAX	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)	0.541(13,74)	0.598(15,19)
	MIN	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)	0.514(13,06)	0.571(14,50)

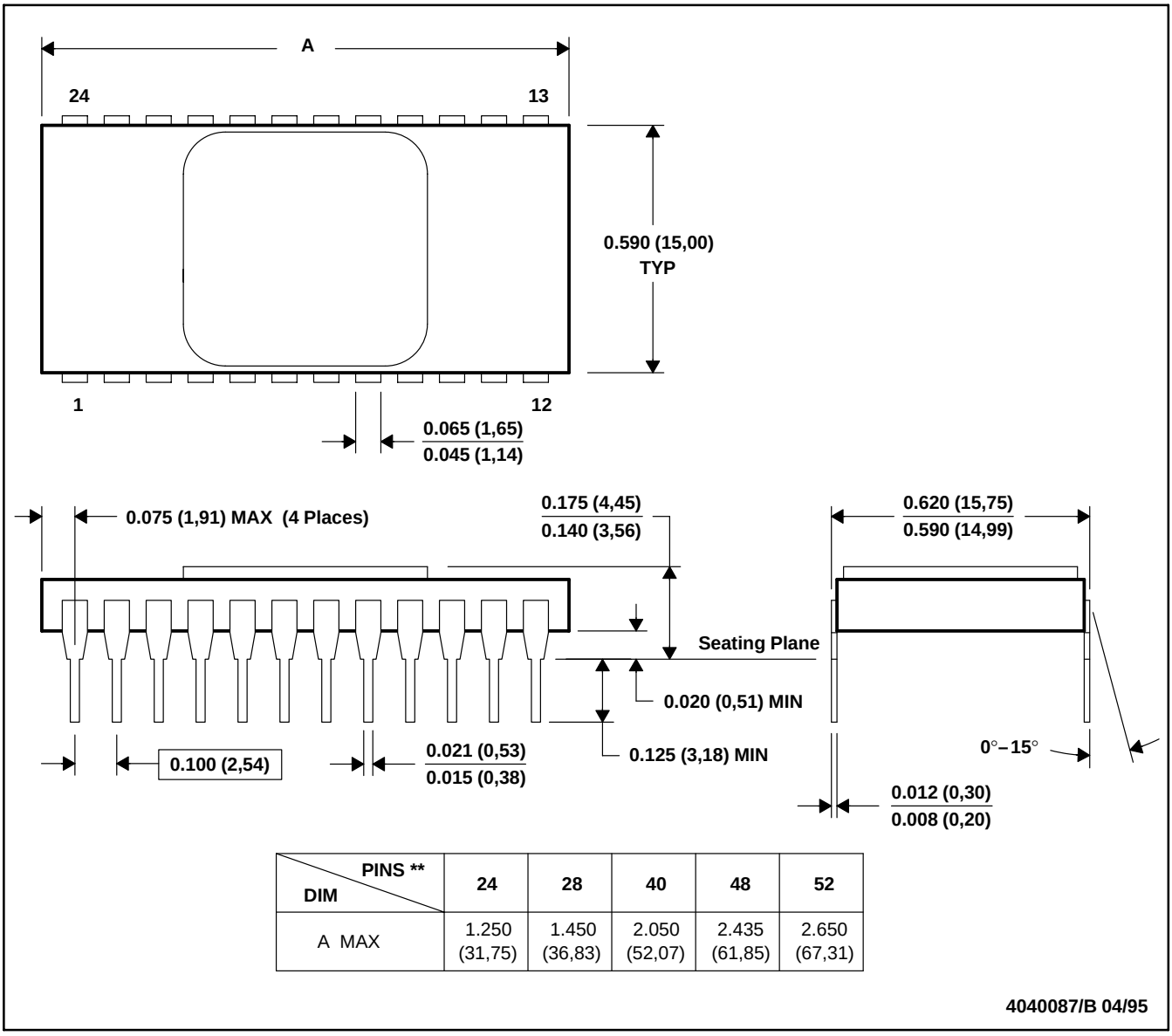
4040084/C 10/97

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).
D. This package can be hermetically sealed with a ceramic lid using glass frit.
E. Index point is provided on cap for terminal identification.

MCDI005 – JANUARY 1998

JD (R-CDIP-T)** **CERAMIC SIDE-BRAZE DUAL-IN-LINE PACKAGE**

24 PINS SHOWN



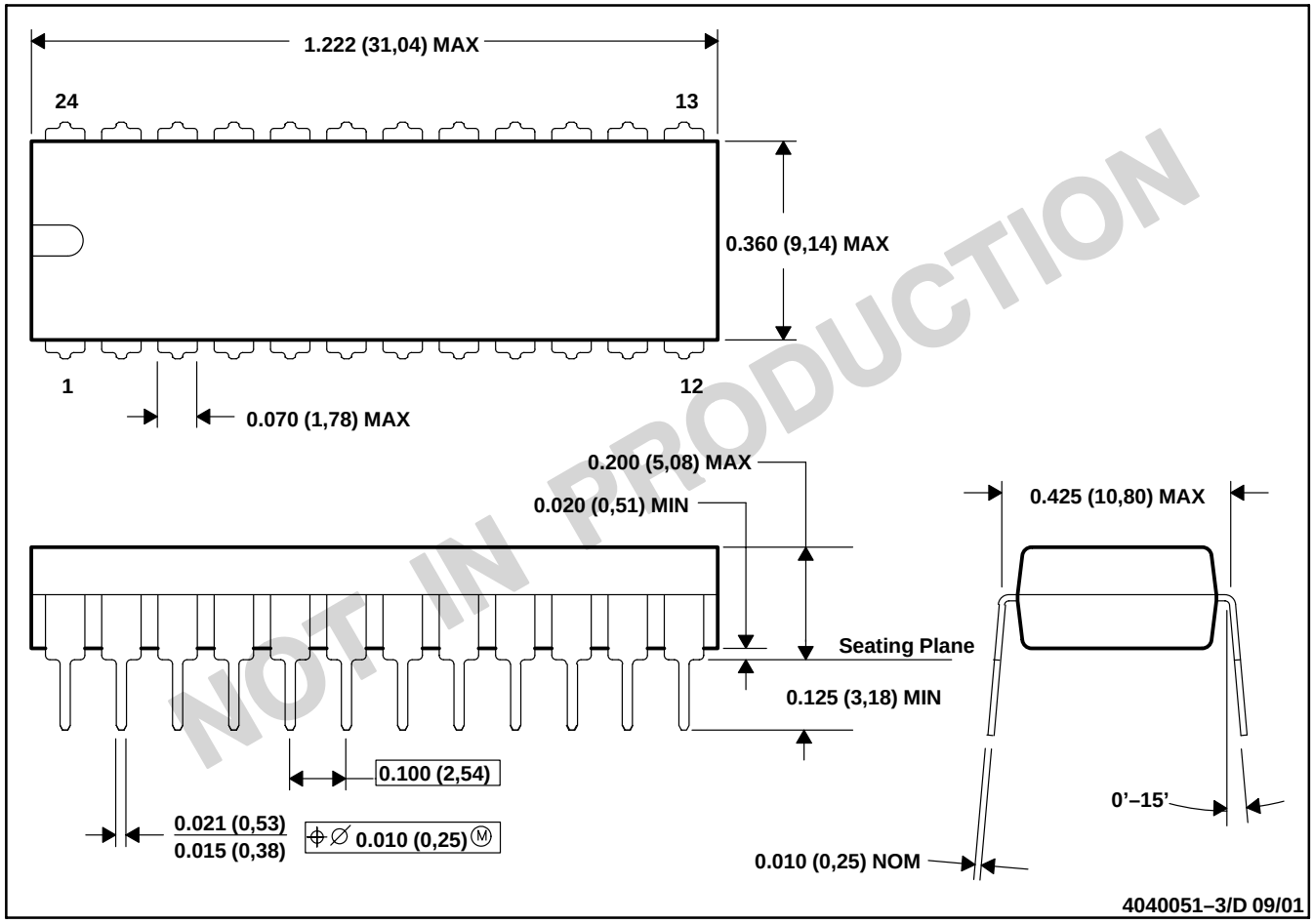
DIM \ PINS **	24	28	40	48	52
A MAX	1.250 (31,75)	1.450 (36,83)	2.050 (52,07)	2.435 (61,85)	2.650 (67,31)

4040087/B 04/95

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a metal lid.
D. The terminals are gold-plated.

MPDI006B – SEPTEMBER 2001 – REVISED APRIL 2002

N (R–PDIP–T24) **PLASTIC DUAL–IN–LINE**

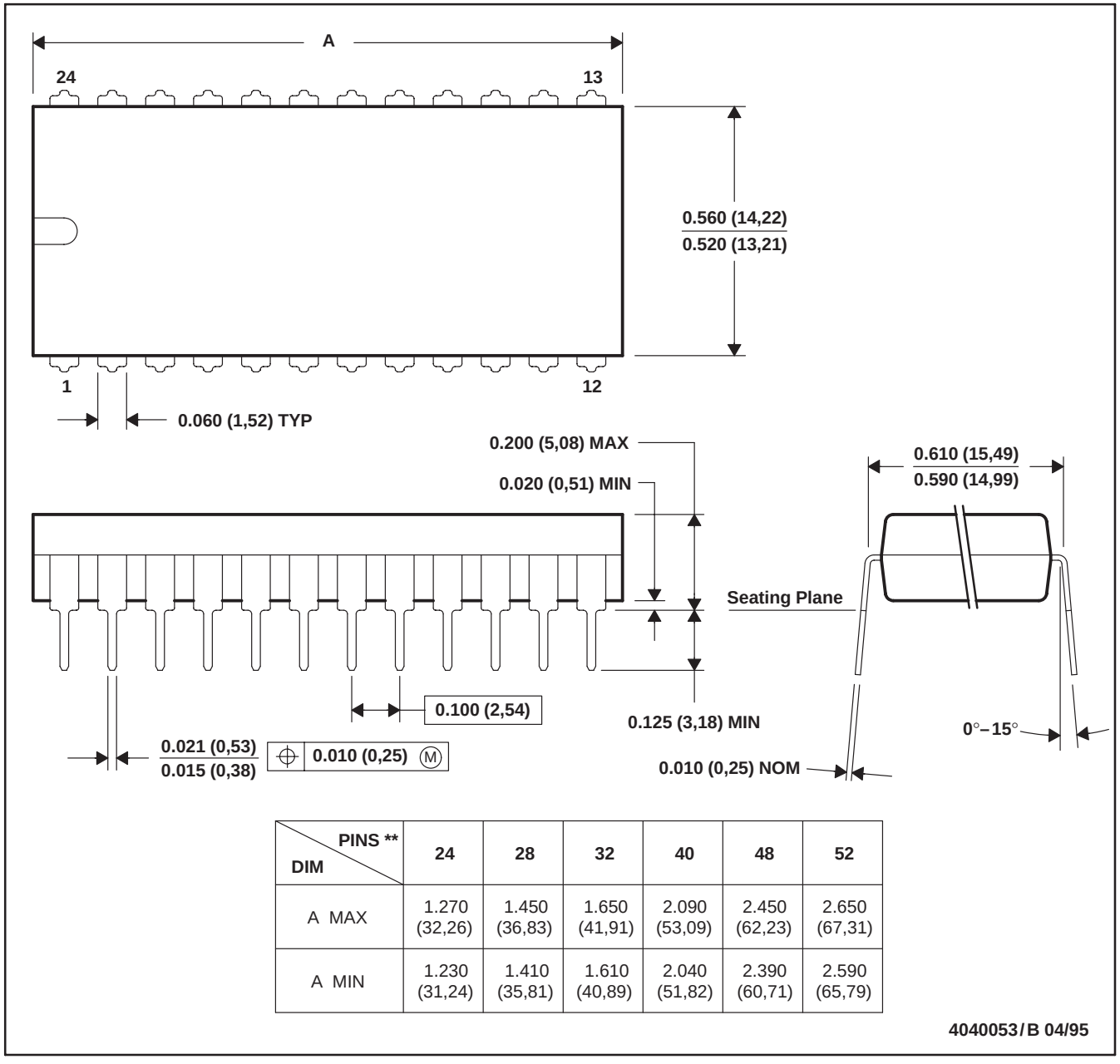


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–010

MPDI008 – OCTOBER 1994

N (R-PDIP-T**) PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN

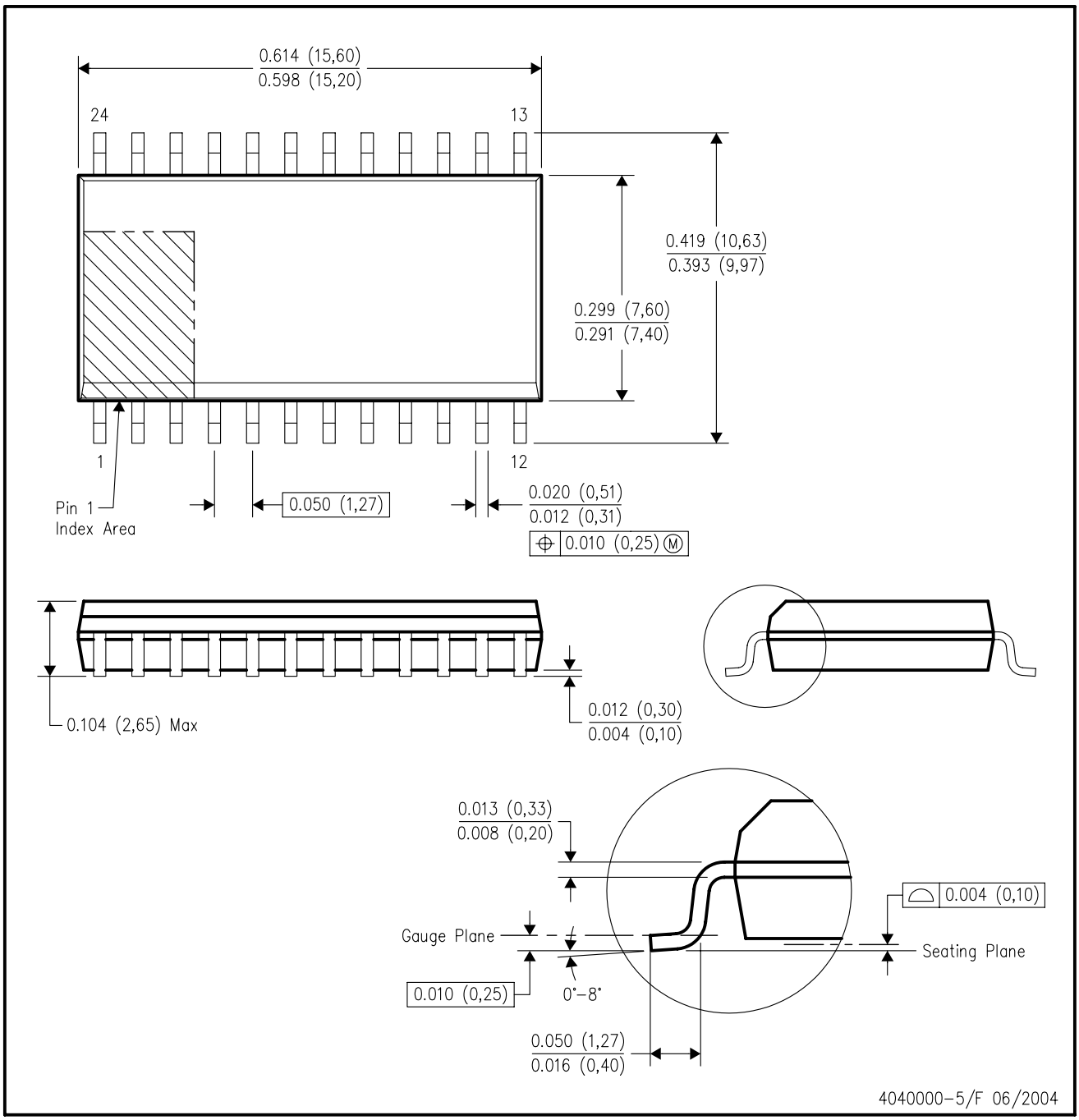


DIM \ PINS **	24	28	32	40	48	52
A MAX	1.270 (32,26)	1.450 (36,83)	1.650 (41,91)	2.090 (53,09)	2.450 (62,23)	2.650 (67,31)
A MIN	1.230 (31,24)	1.410 (35,81)	1.610 (40,89)	2.040 (51,82)	2.390 (60,71)	2.590 (65,79)

4040053/B 04/95

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-011
D. Falls within JEDEC MS-015 (32 pin only)

DW (R–PDSO–G24) PLASTIC SMALL–OUTLINE PACKAGE

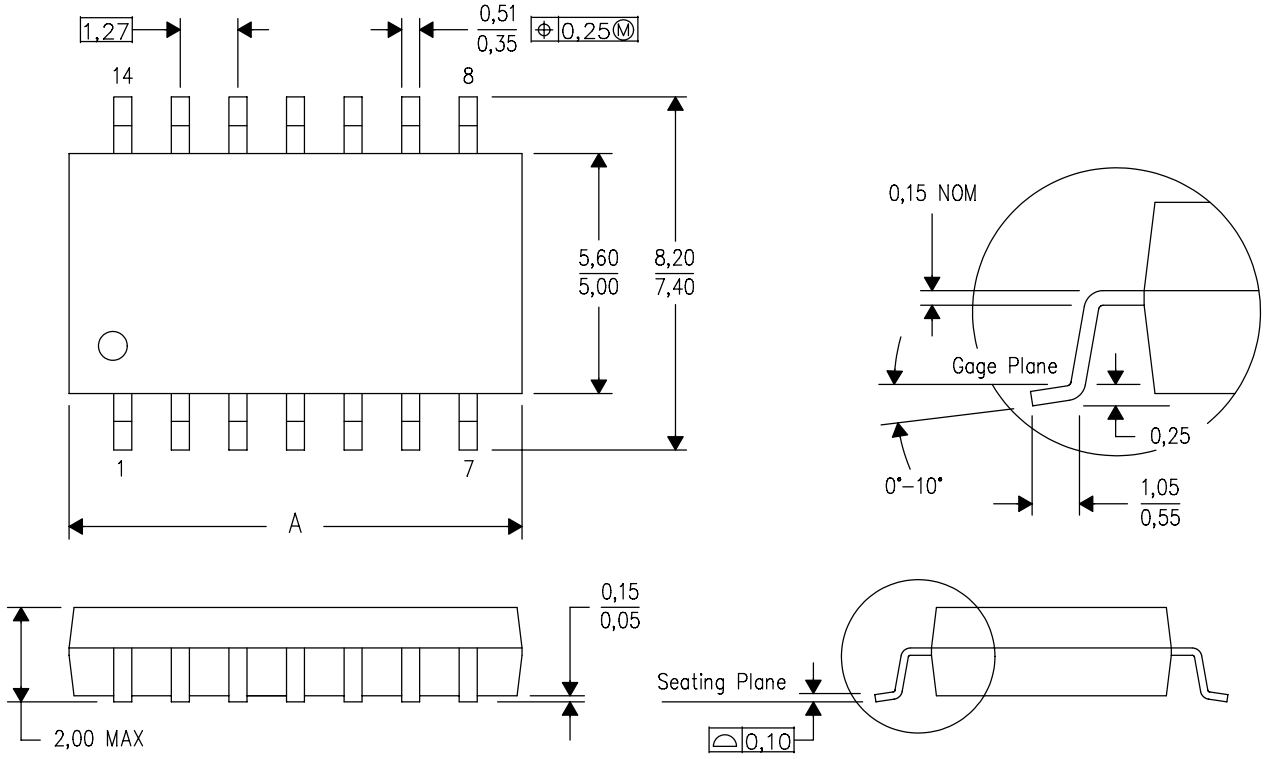


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



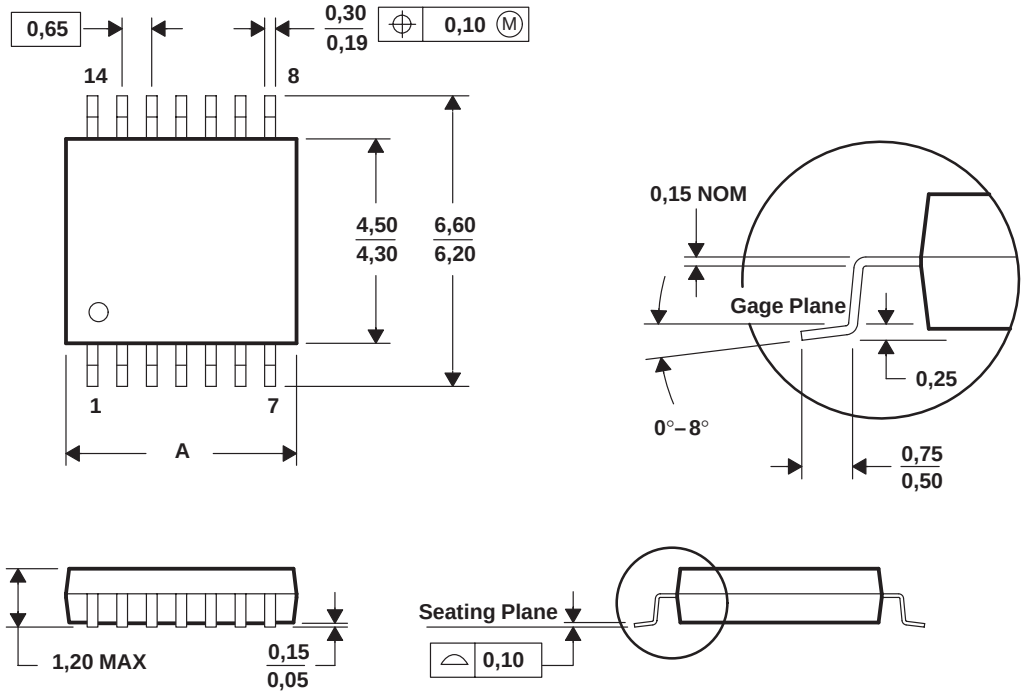
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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